

ABSTRACT

A method of manufacturing a hermetically-sealed optoelectronic package having an insulating base, a metal cap, and a metal layer sandwiched between the metal cap and the insulating base includes supplying a force to push the metal cap against the metal layer and to push the metal layer against the insulating base. A first electrode is applied to the metal cap, and a second electrode is applied to the metal layer. A current is supplied between the first and second electrodes to weld the metal cap to the metal layer.